

# COOL Chips XIII

Yokohama Joho Bunka Center, Yokohama, Japan

(Yokohama Media & Communications Center, Yokohama, Japan)

April 14 - 16, 2010

## CALL FOR CONTRIBUTIONS

COOL Chips is an International Symposium initiated in 1998 to present advancement of low-power and high-speed chips. The symposium covers leading-edge technologies in all areas of microprocessors and their applications. The COOL Chips XIII is to be held in Yokohama on April 14-16, 2010, and is targeted at the architecture, design and implementation of chips with special emphasis on the areas listed below. The COOL Chips Organizing Committee will ask the MICRO to publish selected papers in a special issue on COOL Chips XIII.

### Contributions are solicited in the following areas:

- **Low Power-High Performance Processors, "Eco-Processors", for - Multimedia, Digital Consumer Electronics, Mobile, Graphics, Encryption, Robotics, Automotive, Networking, Medical, Healthcare, and Biometrics.**
- **Novel Architectures and Schemes for - Single Core, Multi-Core, Embedded Systems, Reconfigurable Computing, Grid, Ubiquitous, Dependable Computing, GALS and Wireless.**
- **Cool Software including - Parallel Schedulers, Embedded Real-time Operating System, Binary Translations, Compiler Issues and Low Power Techniques.**

Proposals should consist of a title, an extended abstract (up to 3 pages) describing the product or topic to be presented and the name, job title, address, phone number, FAX number, and e-mail address of the presenter. The status of the product or topic should precisely be described. If this is a not-yet-announced product, and you would like to keep the submission confidential, please indicate it. We will do our best to maintain confidentiality. Proposals will be selected by the program committee's evaluation of interest to the audience. Submission should be made by e-mail, (Author's kit can be obtained from <http://www.coolchips.org/>)

to: Makoto Ikeda, Program Chair **e-mail: [submit\\_xiii@coolchips.org](mailto:submit_xiii@coolchips.org)**  
**Author Schedule: January 15, 2010 Extended Abstract Submission (by e-mail)**  
**March 1, 2010 Acceptance Notified (by e-mail)**  
**March 15, 2010 Final Manuscript Submission**

You are also invited to submit proposals for poster sessions by e-mail, to : M. Muroyama , Poster Chair **e-mail: [poster\\_xiii@coolchips.org](mailto:poster_xiii@coolchips.org)**  
**Author Schedule: March 8, 2010 Poster Abstract Submission (by e-mail)**  
**March 15, 2010 Poster Acceptance Notified (by e-mail)**

For more information, please visit <<http://www.coolchips.org/>>.  
 For any questions, please contact the Secretariat <[cool\\_xiii@coolchips.org](mailto:cool_xiii@coolchips.org)>.

Sponsored by the Technical Committees on Microprocessors and Microcomputers and Computer Architecture of the IEEE Computer Society. In cooperation with the IEICE Electronics Society, ACM SIGARCH and IPSJ.



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